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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
BEFORE THE COMMISSIONER OF PATENTS

Appl. No. : 10/757,586
Applicant : Robert D. Edwards
Filed : 1/15/04
TC/A.U. : 2816
Examiner :
Docket No. : EI-2-04-001
Title: : **Method of Making Printed Circuit Board With Electroplated
Conductive Thru Holes And Board Resulting Therefrom**
Assignee : Endicott Interconnect Technologies, Inc.

Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

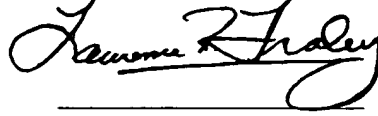
STATUS INQUIRY

Applicants request the status of the above application. The application was filed on 01/15/04. A copy of the return postcard is attached for the Examiner's convenience. A Filing Receipt was received 04/21/04. A copy is attached for the Examiner's convenience. A Change of Correspondence Address was filed 07/12/04. A copy of this return postcard is also attached for the Examiner's convenience.

Because Applicants have heard nothing further as of this date, a status is requested. Please advise when we may expect a communication with respect to the above-referenced application. A stamped, self-addressed envelope is enclosed herewith for your use in responding to this request.

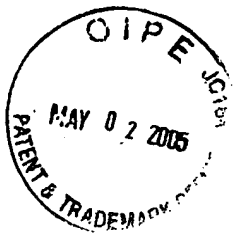
An e-mail response to the undersigned at the email address below or a phone response is encouraged to expedite a response to this inquiry.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Lawrence R. Fraley", written over a horizontal line.

Telephone: (561) 575-3608
Fax : (561) 745-2741

Lawrence R. Fraley
Reg. No: 26,885
Attorney for Applicants
Date: April 28, 2005
e-mail: Lawrence.Fraley@eitny.com



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JAN 27 2004

Date: 1/14/04

~~Express Mail~~ Airborne Airbill #8460322882

Please Acknowledge and Return

- | | |
|---|--|
| <input checked="" type="checkbox"/> Application | <input type="checkbox"/> Issue Fee |
| <input checked="" type="checkbox"/> Declaration <u>2</u> pgs. | <input type="checkbox"/> Draftsman w/Dwgs. |
| <u>X</u> signed <u> </u> unsigned | <input checked="" type="checkbox"/> Cert. Of Mailing |
| <input checked="" type="checkbox"/> Assignment w/Cover Pg. | <input type="checkbox"/> |
| <input checked="" type="checkbox"/> IDS/PTO-1449/Refs. | |
| <input type="checkbox"/> Amendment | |

Received by U.S.
Patent Office

Title Method of Making Printed Circuit Board With 19270
Electroplated Conductive Thru Holes And Board
Resulting Therefrom 10/757586

17 Pgs. Spec. 18 Claims 2 Shts. Of Drawing
Filing Fee Attorney Lawrence Fraley
Docket SI-2-04-001
In Appln. Of Robert D. Edwards
Serial/Inter. Number
Filed Herewith
Deposit account 09-0457



011504

Date: 7/8/04
Express Mail No.: _____

Please Acknowledge and Return

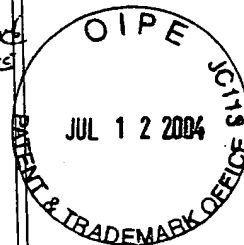
- ☐ Application
☐ Declaration ____ pgs.
____ signed ____ unsigned
☐ Assignment w/Cover Pg.
☐ IDS/PTO-1449/Refs.
☐ Amendment

- ☐ Issue Fee
☐ Draftsman w/Dwgs.
☒ Cert. of Mailing
☒ Change of
Correspondence
Address

Title Method of Making Printed Circuit Board
With Electroplated Conductive Thru Holes
And Board Resulting Therefrom

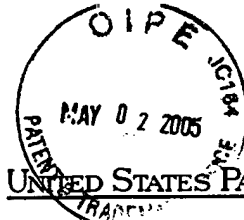
____ Pgs. Spec. ____ Claims ____ Shts. of Drawing
Filing Fee Attorney Lawrence Fratey
Docket EI-2-04-001
In Appln. Of R. Edwards
Serial/Inter. Number 10/757,586
Filed 1/15/01

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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/757,586	01/15/2004	2816	770	EI-2-04-001	2	18	2

CONFIRMATION NO. 4656

FILING RECEIPT



OC000000012390522

Lawrence R. Fraley, IP Law Counsel
 Endicott Interconnect Technologies, Inc.
 FBU/257-2 AA12
 1701 North Street
 Endicott, NY 13760

Date Mailed: 04/19/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Robert D. Edwards, Binghamton, NY;

Assignment For Published Patent Application

Endicott Interconnect Technologies, Inc., Endicott, NY;

Domestic Priority data as claimed by applicant

Foreign Applications

If Required, Foreign Filing License Granted: 04/19/2004

Projected Publication Date: 07/21/2005

Non-Publication Request: No

Early Publication Request: No

Title

Method of making printed circuit board with electroplated conductive through holes and board resulting therefrom



Certificate of Mailing under 37 CFR 1.8

I hereby certify that this correspondence is being deposited with United States Postal Service in an envelope addressed to:

**Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450**

On April 28, 2005.

Signature

Christine Lang

Typed or printed name of person of signing Certificate

EI-2-04-001 – Status Inquiry, Post Card, Copy of Application Return Post Card, Copy of Filing Receipt, Copy of Change of Correspondence Address Post Card, Stamped, Self-Addressed Envelope.

Note: Each paper must have its own certificate of mailing, or this certificate must identify each submitted paper.